

Ceramic Plate Series Thermoelectric Cooler

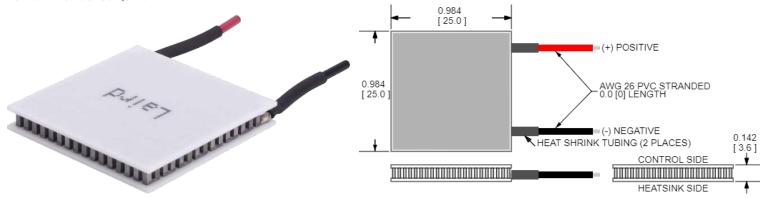
The CP08-127-06-MM-EP W4.5 is a high-performance and highly reliable standard Thermoelectric Cooler. Assembled with Bismuth Telluride semiconductor material and thermally conductive Aluminum Oxide ceramics. It has a maximum Qc of 17.5 Watts when $\Delta T=0$ and a maximum ΔT of 70.5 °C at Qc = 0.

Features

- Compact geometric sizes
- DC Operation
- RoHS-compliant

Applications

- Thermoelectric Coolers for Reagent Storage
- Thermoelectric Coolers for Handheld Cosmetic Lasers
- Cooling for Centrifuges
- Heads-Up Displays, Imaging Sensors
- Peltier Cooling for Machine Vision

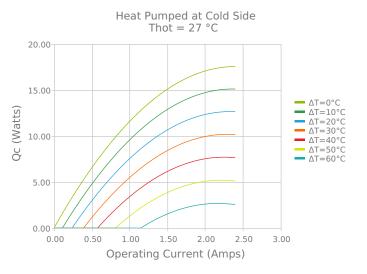


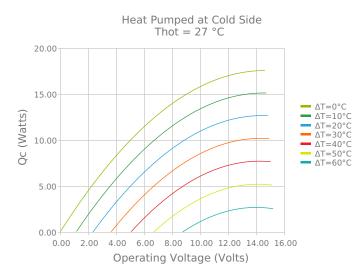
CERAMIC MATERIAL: Al₂O₃ SOLDER CONSTRUCTION: 138°C, BiSn

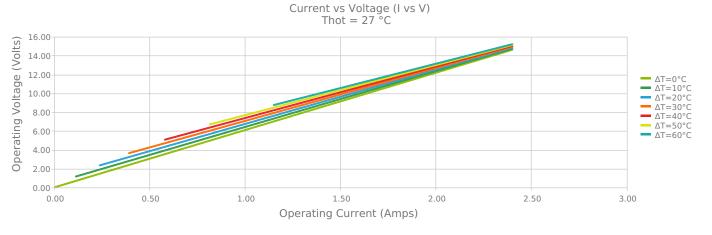
INCHES [MM]

ELECTRICAL AND THERMAL PERFORMANCE

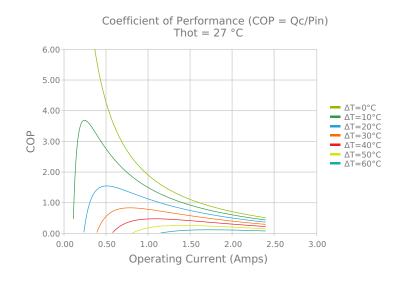
For maximum performance, be sure to orient the CONTROL side of the TEC against the application to be managed and the HEATSINK side against the heat sink or other heat rejection method. The CONTROL side is always opposite the side with lead attachments. Lead attachment is a passive heat loss and less impactful if located on the side that attaches to the heat exchanger.

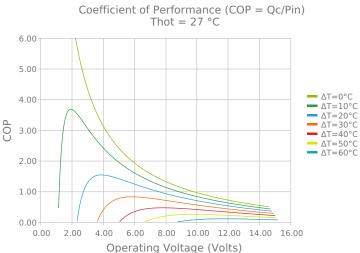


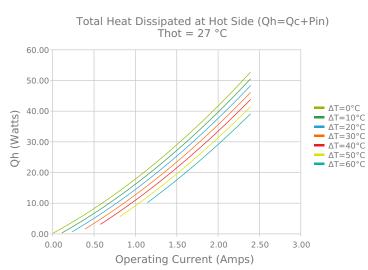


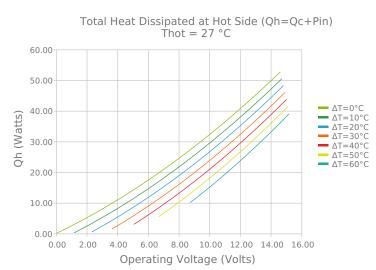


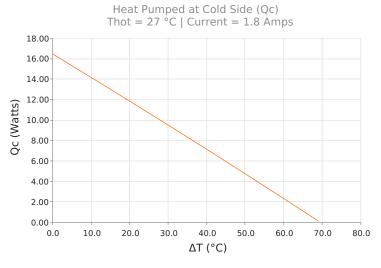


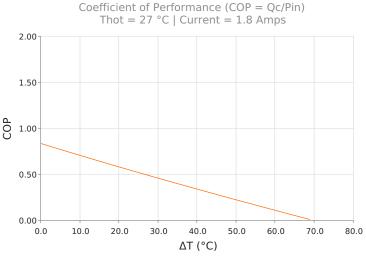














SPECIFICATIONS*

Hot Side Temperature

 $Qcmax (\Delta T = 0)$

 $\Delta T max (Qc = 0)$

Imax (I @ ATmax)

Vmax (V @ Δ Tmax)

Module Resistance

Max Operating Temperature

Weight

27.0 °C	35.0 °C	50.0 °C
17.5 Watts	18.1 Watts	19.0 Watts
70.5°C	73.5°C	78.8°C
2.1 Amps	2.1 Amps	2.1 Amps
13.9 Volts	14.4 Volts	15.4 Volts
6.09 Ohms	6.34 Ohms	6.82 Ohms
80 °C		
7.0 gram(s)		

FINISHING OPTIONS

Suffix	Thickness	Flatness / Parallelism	Hot Face	Cold Face	Lead Length
MM	3.606 ±0.254 mm 0.142 ± 0.0100 in	0.051 mm / 0.051 mm 0.002 in / 0.002 in	Metallized	Metallized	114.3 mm 4.50 in

SEALING OPTIONS

Suffix	Sealant	Color	Temp Range	Description
None			No sealing specified	

NOTES

- 1. Max operating temperature: 80°C
- 2. Do not exceed Imax or Vmax when operating module
- 3. Reference assembly guidelines for recommended installation
- 4. Solder tinning also available on metallized ceramics

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Revision: 00 Date: 06-01-2022

Print Date: 06-09-2022

^{*} Specifications reflect thermoelectric coefficients updated March 2020